imall

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CLC1007, CLC2007, CLC4007 Single, Dual, and Quad Low Cost,

High Speed RRO Amplifiers

General Description

The CLC1007 (single), CLC2007 (dual) and CLC4007(guad) are low cost, voltage feedback amplifiers. These amplifiers are designed to operate on +3V to +5V, or ±5V supplies. The input voltage range extends 300mV below the negative rail and 0.9V below the positive rail.

The CLC1007, CLC2007, and CLC4007 offer superior dynamic performance with a 260MHz small signal bandwidth and 220V/µs slew rate. The combination of low power, high output current drive, and rail-torail performance make these amplifiers well suited for battery-powered communication/computing systems.

The combination of low cost and high performance make the CLC1007. CLC2007, and CLC4007 suitable for high volume applications in both consumer and industrial applications such as wireless phones, scanners, color copiers, and video transmission.

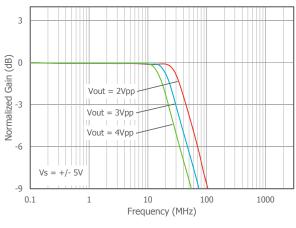
FEATURES

- 260MHz bandwidth
- Fully specified at +3V, +5V and ±5V supplies
- Output voltage range: • 0.03V to 4.95V; $V_S = +5$; $R_L = 2k\Omega$
- Input voltage range:
- -0.3V to +4.1V; V_S = +5
- 220V/us slew rate
- 2.6mA supply current per amplifier
- ±100mA linear output current
- ±125mA short circuit current
- CLC2007 directly replaces LMH6643, AD8042, AD8052, and AD8092
- CLC1007 directly replaces LMH6642, AD8041, AD8051, and AD8091

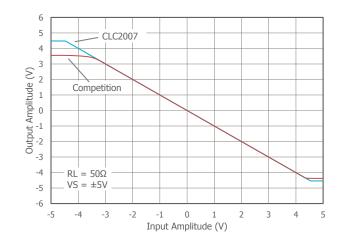
APPLICATIONS

- A/D driver
- Active filters
- CCD imaging systems
- CD/DVD ROM
- Coaxial cable drivers
- High capacitive load driver
- Portable/battery-powered applications
- Twisted pair driver
- Telecom and optical terminals
- Video driver

Ordering Information - page 26



Output Voltage Swing vs Competition Large Signal Frequency Response



Absolute Maximum Ratings

Stresses beyond the limits listed below may cause permanent damage to the device. Exposure to any Absolute Maximum Rating condition for extended periods may affect device reliability and lifetime.

V _S	0V to +14V
V _{IN}	-V _S - 0.5V to +V _S +0.5V

Operating Conditions

Supply Voltage Range	2.7 to 12.6V
Operating Temperature Range	40°C to 125°C
Junction Temperature	150°C
Storage Temperature Range	65°C to 150°C
Lead Temperature (Soldering, 10s)	260°C

Package Thermal Resistance

θ _{JA} (TSOT23-5)	215°C/W
θ _{JA} (SOIC-8)	150°C/W
θ _{JA} (MSOP-8)	200°C/W
θ _{JA} (SOIC-14)	90°C/W
θ _{JA} (TSSOP-14)	100°C/W
Package thermal resistance ($\theta_{JA}),\ JEDEC$ standard, test boards, still air.	multi-layer

ESD Protection

TSOT-5 (HBM)	1kV
SOIC-8 (HBM)	1kV
TSOT-5 (CDM)	2kV
SOIC-8 (CDM)	2kV
ESD Rating for HBM (Human Body Model) Device Model).	and CDM (Charged

Electrical Characteristics at +3V

 T_A = 25°C, V_S = +3V, R_f = 1.5k $\Omega,~R_L$ = 2k Ω to $V_S/2;~G$ = 2; unless otherwise noted.

Symbol	Parameter	Conditions	Min	Тур	Max	Units
Frequency	Domain Response					
GBWP	-3dB Gain Bandwidth Product	$G = +11, V_{OUT} = 0.2V_{pp}$		90		MHz
UGBW	Unity Gain Bandwidth	$V_{OUT} = 0.2V_{pp}, R_F = 0$		245		MHz
BW _{SS}	-3dB Bandwidth	$V_{OUT} = 0.2V_{pp}$		85		MHz
f _{0.1dB}	0.1dB Gain Flatness	$V_{OUT} = 0.2V_{pp}, R_L = 150\Omega$		16		MHz
BW _{LS}	Large Signal Bandwidth	$V_{OUT} = 2V_{pp}$		55		MHz
D 0	Differential Option	DC-coupled Output		0.03		%
DG	Differential Gain	AC-coupled Output		0.04		%
D D	D'fferentiel Disease	DC-coupled Output		0.03		0
DP	Differential Phase	AC-coupled Output		0.06		0
Time Doma	in					
t _R , t _F	Rise and Fall Time	V _{OUT} = 0.2V step; (10% to 90%)		5		ns
t _S	Settling Time to 0.1%	V _{OUT} = 1V step		25		ns
OS	Overshoot	V _{OUT} = 0.2V step		8		%
SR	Slew Rate	G = -1, 2V step		175		V/µs
Distortion/N	loise Response		1			
THD	Total Harmonic Distortion	$1MHz, V_{OUT} = 1V_{pp}$		75		dBc
e _n	Input Voltage Noise	>50kHz		16		nV/√Hz
X _{TALK}	Crosstalk	f = 5MHz		58		dB
DC Perform	ance				<u> </u>	
V _{IO}	Input Offset Voltage			0.5		mV
d _{VIO}	Average Drift			5		μV/°C
IB	Input Bias Current			1.4		μA
dl _B	Average Drift			2		nA/°C
I _{OS}	Input Offset Current			0.05		μA
PSRR	Power Supply Rejection Ratio	DC		102		dB
A _{OL}	Open Loop Gain	$R_L = 2k\Omega$		92		dB
I _S	Supply Current	per channel		2.6		mA
Input Chara	acteristics		1			
C _{IN}	Input Capacitance			0.5		pF
CMIR	Common Mode Input Range			-0.3 to 2.1		V
CMRR	Common Mode Rejection Ratio	DC, V _{CM} = 0 to 1.5V		100		dB
Output Cha			I	1	I	1
		R _L = 150Ω		0.3 to		v
V _{OUT}	Output Swing	Π <u></u> = 10022		2.75		· ·
001		$R_L = 2k\Omega$		0.02 to 2.96		V
I _{OUT}	Output Current			±100		mA
I _{SC}	Short Circuit Current	$V_{OUT} = V_S / 2$		±125		V
V _S	Power Supply Operating Range			2.7 to 12.6		V

Electrical Characteristics at +5V

 T_A = 25°C, V_S = +5V, R_f = 1.5k $\Omega,~R_L$ = 2k Ω to $V_S/2;~G$ = 2; unless otherwise noted.

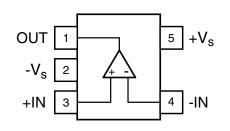
Symbol	Parameter	Conditions	Min	Тур	Max	Units
Frequency	Domain Response					
GBWP	-3dB Gain Bandwidth Product	$G = +11, V_{OUT} = 0.2V_{pp}$		95		MHz
UGBW	Unity Gain Bandwidth	$V_{OUT} = 0.2V_{pp}, R_F = 0$		250		MHz
BW _{SS}	-3dB Bandwidth	$V_{OUT} = 0.2V_{pp}$		85		MHz
f _{0.1dB}	0.1dB Gain Flatness	$V_{OUT} = 0.2V_{pp}, R_L = 150\Omega$		35		MHz
BW _{LS}	Large Signal Bandwidth	$V_{OUT} = 2V_{pp}$		65		MHz
		DC-coupled Output		0.03		%
DG	Differential Gain	AC-coupled Output		0.04		%
55	D'//	DC-coupled Output		0.03		0
DP	Differential Phase	AC-coupled Output		0.06		0
Time Doma	in					,
t _R , t _F	Rise and Fall Time	V _{OUT} = 0.2V step		5		ns
t _S	Settling Time to 0.1%	V _{OUT} = 2V step		25		ns
OS	Overshoot	V _{OUT} = 0.2V step		5		%
SR	Slew Rate	G = -1, 4V step		220		V/µs
Distortion/N	loise Response					
THD	Total Harmonic Distortion	$1MHz, V_{OUT} = 2V_{pp}$		-75		dBc
e _n	Input Voltage Noise	>50kHz		16		nV/√Hz
X _{TALK}	Crosstalk	f = 5MHz		58		dB
DC Perform	hance					,
V _{IO}	Input Offset Voltage		-7	0.5	7	mV
d _{VIO}	Average Drift			5		μV/°C
I _B	Input Bias Current		-2	1.4	2	μA
dl _B	Average Drift			2		nA/°C
I _{OS}	Input Offset Current		-0.75	0.05	0.75	μΑ
PSRR	Power Supply Rejection Ratio	DC	80	102		dB
A _{OL}	Open Loop Gain	$R_L = 2k\Omega$	80	92		dB
I _S	Supply Current	per channel		2.6	4	mA
Input Chara	acteristics					
C _{IN}	Input Capacitance			0.5		pF
CMIR	Common Mode Input Range			-0.3 to 4.1		V
CMRR	Common Mode Rejection Ratio	DC, V _{CM} = 0 to 3.5V	75	100		dB
Output Cha			I	<u> </u>		1
		R _L = 150Ω	0.35	0.1 to 4.9	4.65	v
V _{OUT}	Output Swing	$R_L = 2k\Omega$		0.03 to 4.95		V
I _{OUT}	Output Current			±100		mA
I _{SC}	Short Circuit Current	$V_{OUT} = V_S / 2$		±125		V
V _S	Power Supply Operating Range			2.7 to 12.6		V

Electrical Characteristics at ±5V

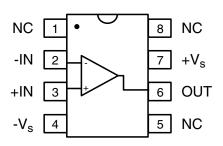
 T_A = 25°C, V_S = ±5V, R_f = 1.5k $\Omega,~R_L$ = 2k Ω to GND; G = 2; unless otherwise noted.

Symbol	Parameter	Conditions	Min	Тур	Max	Units
Frequency	Domain Response					
GBWP	-3dB Gain Bandwidth Product	G = +11, V _{OUT} = 0.2V _{pp}		90		MHz
UGBW	Unity Gain Bandwidth	$V_{OUT} = 0.2V_{pp}, R_F = 0$		260		MHz
BW _{SS}	-3dB Bandwidth	$V_{OUT} = 0.2V_{pp}$		85		MHz
f _{0.1dB}	0.1dB Gain Flatness	$V_{OUT} = 0.2V_{pp}, R_L = 150\Omega$		22		MHz
BW _{LS}	Large Signal Bandwidth	$V_{OUT} = 2V_{pp}$		65		MHz
50		DC-coupled Output		0.03		%
DG	Differential Gain	AC-coupled Output		0.04		%
		DC-coupled Output		0.03		0
DP	Differential Phase	AC-coupled Output		0.06		0
Time Doma	in					
t _R , t _F	Rise and Fall Time	V _{OUT} = 0.2V step		5		ns
t _S	Settling Time to 0.1%	$V_{OUT} = 2V$ step, $R_L = 100\Omega$		25		ns
OS	Overshoot	V _{OUT} = 0.2V step		5		%
SR	Slew Rate	G = -1, 5V step		225		V/µs
Distortion/N	loise Response		· · · ·			
THD	Total Harmonic Distortion	$1MHz, V_{OUT} = 2V_{pp}$		76		dBc
e _n	Input Voltage Noise	>50kHz		16		nV/√H
X _{TALK}	Crosstalk	f = 5MHz		58		dB
DC Perform	ance		· · · ·			
V _{IO}	Input Offset Voltage			0.5		mV
d _{VIO}	Average Drift			5		μV/°C
I _B	Input Bias Current			1.3		μA
dl _B	Average Drift			2		nA/°C
I _{OS}	Input Offset Current			0.04		μA
PSRR	Power Supply Rejection Ratio	DC		102		dB
A _{OL}	Open Loop Gain	$R_L = 2k\Omega$		92		dB
I _S	Supply Current	per channel		2.6		mA
Input Chara	acteristics		· · · ·			
C _{IN}	Input Capacitance			0.5		pF
CMIR	Common Mode Input Range			-5.3 to 4.1		V
CMRR	Common Mode Rejection Ratio	DC, V _{CM} = -5 to 3.5V		100		dB
Output Cha	racteristics		· · · ·			
-		R _L = 150Ω		-4.8 to 4.8		v
V _{OUT}	Output Swing	$R_L = 2k\Omega$		-4.95 to 4.93		V
I _{OUT}	Output Current			±100		mA
I _{SC}	Short Circuit Current	$V_{OUT} = V_S / 2$		±125		V
V _S	Power Supply Operating Range			2.7 to 12.6		V

CLC1007 Pin Configurations TSOT-5



SOIC-8



CLC1007 Pin Assignments

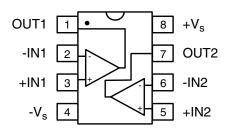
TSOT-5

Pin No.	Pin Name	Description
1	OUT	Output
2	-V _S	Negative supply
3	+IN	Positive input
4	-IN	Negative input
5	+V _S	Positive supply

SOIC-8

Pin No.	Pin Name	Description
1	NC	No Connect
2	-IN	Negative input
3	+IN	Positive input
4	-V _S	Negative supply
5	NC	No Connect
6	OUT	Output
7	+V _S	Positive supply
8	NC	No Connect

CLC2007 Pin Configuration SOIC-8 / MSOP-8



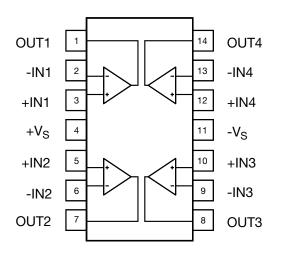
CLC2007 Pin Assignments

SOIC-8 / MSOP-8

Pin No.	Pin Name	Description
1	OUT1	Output, channel 1
2	-IN1	Negative input, channel 1
3	+IN1	Positive input, channel 1
4	-V _S	Negative supply
5	+IN2	Positive input, channel 2
6	-IN2	Negative input, channel 2
7	OUT2	Output, channel 2
8	+V _S	Positive supply

Rev 1D

CLC4007 Pin Configuration SOIC-14/TSSOP-14



CLC4007 Pin Assignments

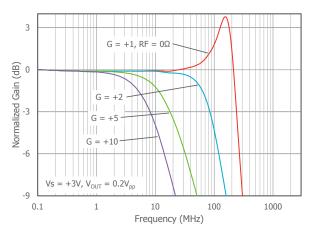
SOIC-14 / TSSOP-14

Pin No.	Pin Name	Description
1	OUT1	Output, channel 1
2	-IN1	Negative input, channel 1
3	+IN1	Positive input, channel 1
4	+V _S	Positive supply
5	+IN2	Positive input, channel 2
6	-IN2	Negative input, channel 2
7	OUT2	Output, channel 2
8	OUT3	Output, channel 3
9	-IN3	Negative input, channel 3
10	+IN3	Positive input, channel 3
11	-V _S	Negative supply
12	+IN4	Positive input, channel 4
13	-IN4	Negative input, channel 4
14	OUT4	Output, channel 4

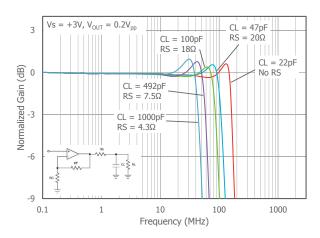
Typical Performance Characteristics at +3V

 $T_A = 25^{\circ}C$, $V_S = +3V$, $R_L = 2k\Omega$ to $V_S/2$, G = +2, $R_F = 1.5k\Omega$; unless otherwise noted.

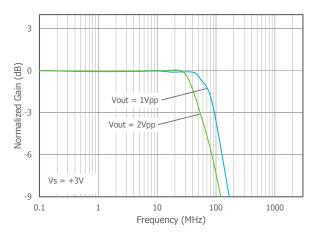
Non-Inverting Frequency Response



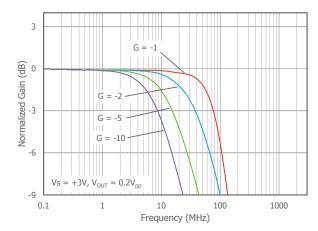
Frequency Response vs CL



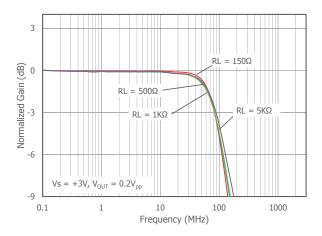
Large Signal Frequency Response



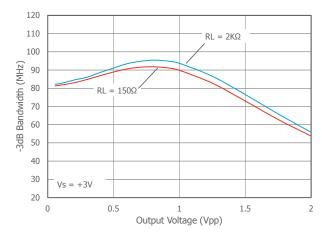
Inverting Frequency Response



Frequency Response vs RL



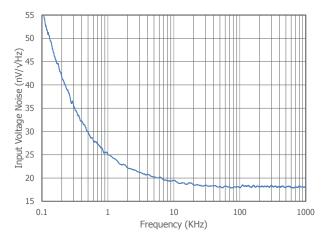




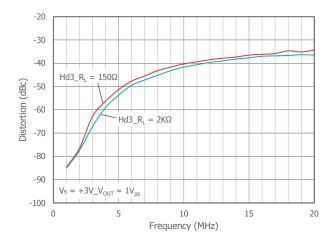
Typical Performance Characteristics at +3V

 T_A = 25°C, V_S = +3V, R_L = 2k Ω to $V_S/2,~G$ = +2, R_F = 1.5k $\Omega;$ unless otherwise noted.

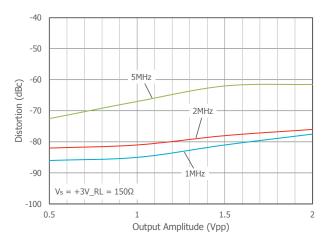
Input Voltage Noise vs Frequency



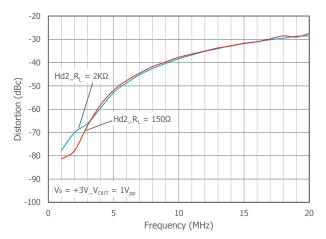
3rd Harmonic Distortion vs RL over Frequency



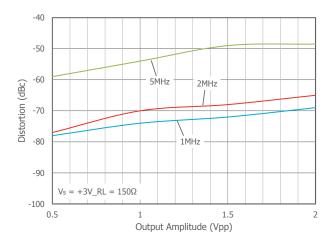
3rd Harmonic Distortion vs VO over Frequency



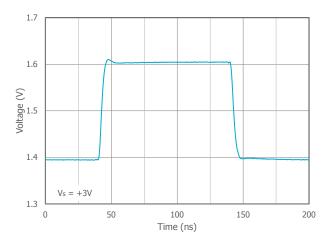
2nd Harmonic Distortion vs RL over Frequency



2nd Harmonic Distortion vs VO over Frequency



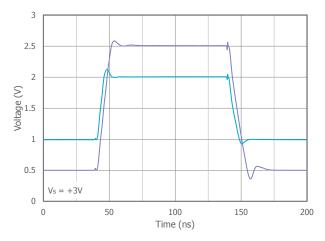
Non-Inverting Small Signal Pulse Response



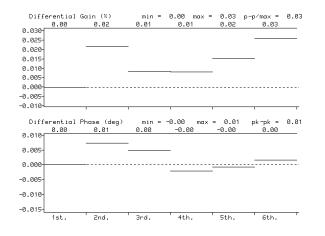
Typical Performance Characteristics at +3V

 $T_A = 25^{\circ}C$, $V_S = +3V$, $R_L = 2k\Omega$ to $V_S/2$, G = +2, $R_F = 1.5k\Omega$; unless otherwise noted.

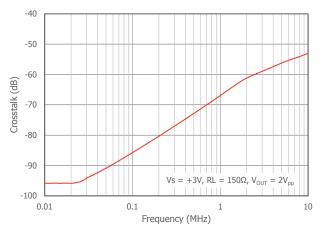
Non-Inverting Large Signal Pulse Response



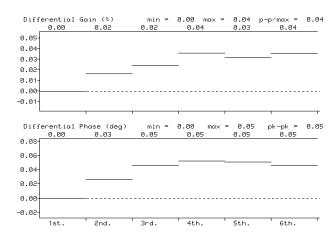
Differential Gain & Phase_DC Coupled



Crosstalk vs Frequency (CLC2007)



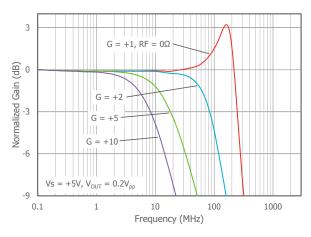
Differential Gain & Phase_AC Coupled



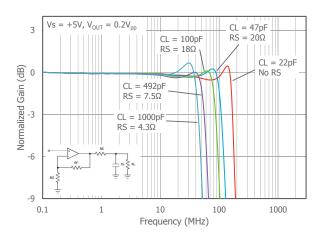
Typical Performance Characteristics at +5V

 $T_A = 25^{\circ}C$, $V_S = +5V$, $R_L = 2k\Omega$ to $V_S/2$, G = +2, $R_F = 1.5k\Omega$; unless otherwise noted.

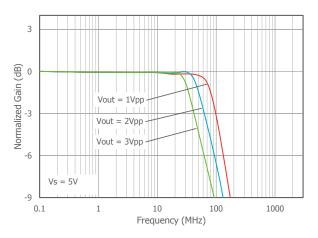
Non-Inverting Frequency Response



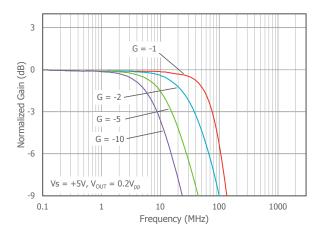
Frequency Response vs CL



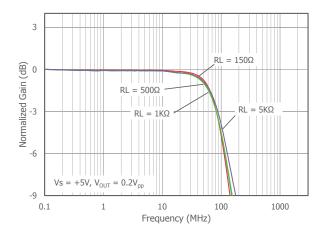
Large Signal Frequency Response



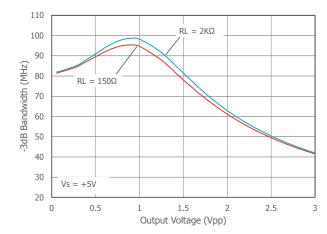
Inverting Frequency Response



Frequency Response vs RL



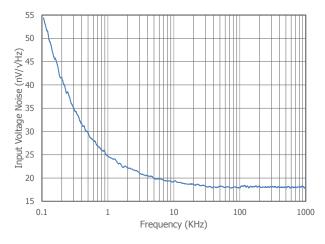
-3dB BW vs Output Voltage



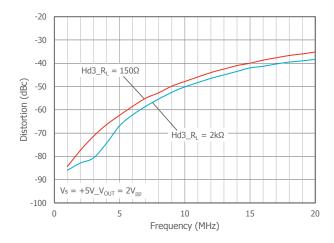
Typical Performance Characteristics at +5V

 T_A = 25°C, V_S = +5V, R_L = 2k Ω to $V_S/2,~G$ = +2, R_F = 1.5k $\Omega;$ unless otherwise noted.

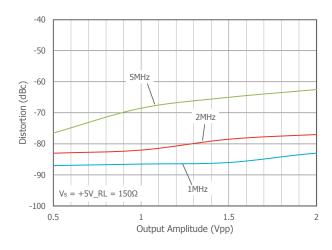
Input Voltage Noise vs Frequency



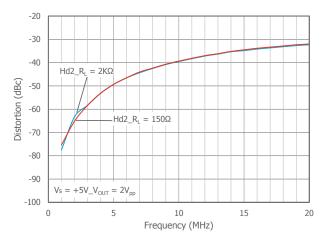
3rd Harmonic Distortion vs $\rm R_L$ over Frequency



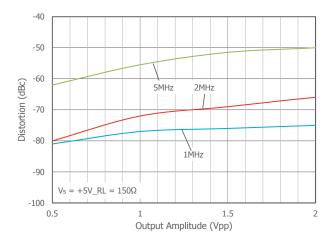
3rd Harmonic Distortion vs VO over Frequency



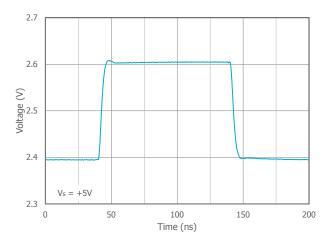
2nd Harmonic Distortion vs RL over Frequency



2nd Harmonic Distortion vs VO over Frequency



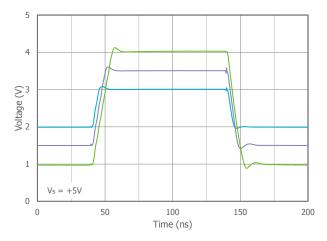
Non-Inverting Small Signal Pulse Response



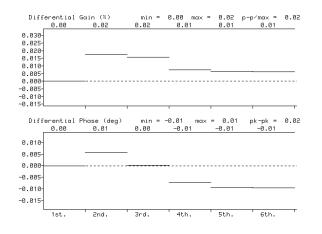
Typical Performance Characteristics at +5V

 T_A = 25°C, V_S = +5V, R_L = 2k Ω to $V_S/2,~G$ = +2, R_F = 1.5k $\Omega;$ unless otherwise noted.

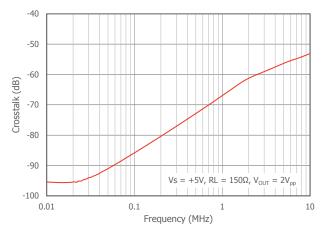
Non-Inverting Large Signal Pulse Response



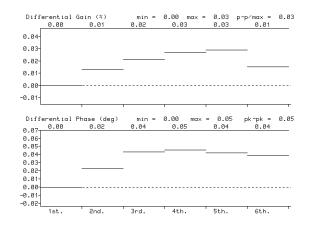
Differential Gain & Phase_DC Coupled



Crosstalk vs Frequency (CLC2007)



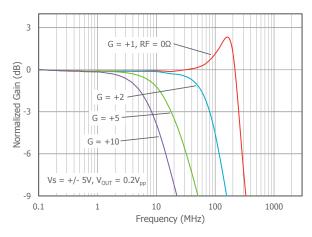
Differential Gain & Phase_AC Coupled



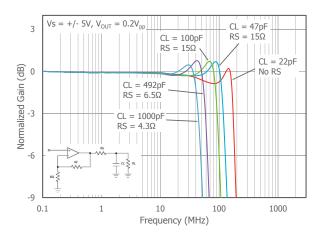
Typical Performance Characteristics at ±5V

 $T_A = 25^{\circ}C$, $V_S = \pm 5V$, $R_L = 2k\Omega$ to GND, G = +2, $R_F = 1.5k\Omega$; unless otherwise noted.

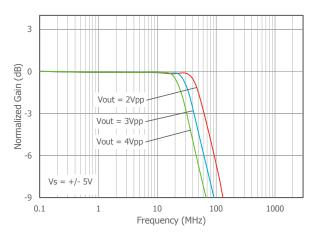
Non-Inverting Frequency Response



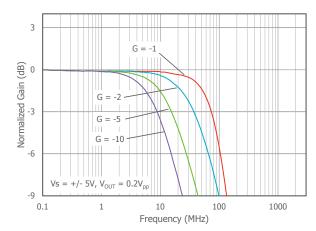
Frequency Response vs CL



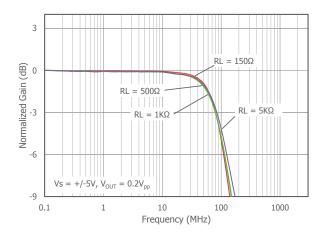
Large Signal Frequency Response



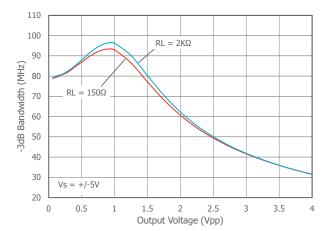
Inverting Frequency Response



Frequency Response vs R_L



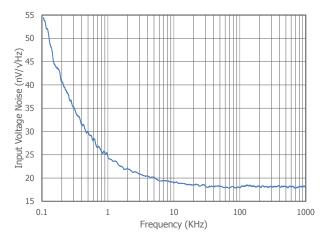




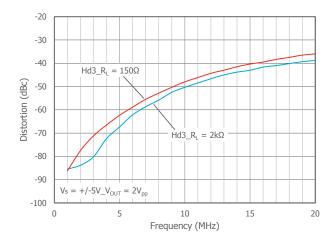
Typical Performance Characteristics at ±5V

 T_A = 25°C, V_S = ±5V, R_L = 2k Ω to GND, G = +2, R_F = 1.5k Ω ; unless otherwise noted.

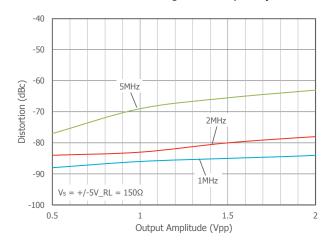
Input Voltage Noise vs Frequency



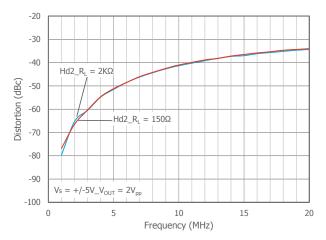
3rd Harmonic Distortion vs R_L over Frequency



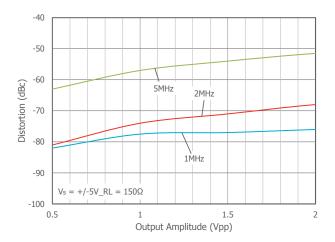
3rd Harmonic Distortion vs VO over Frequency



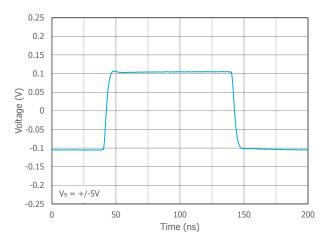
2nd Harmonic Distortion vs RL over Frequency



2nd Harmonic Distortion vs VO over Frequency



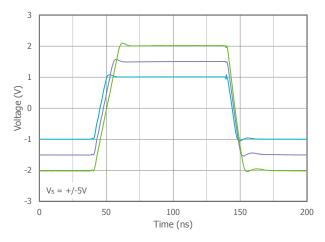
Non-Inverting Small Signal Pulse Response



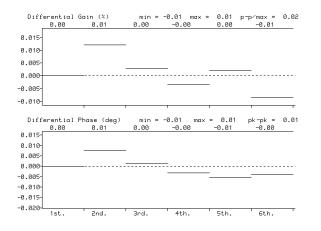
Typical Performance Characteristics at ±5V

 $T_A = 25^{\circ}C$, $V_S = \pm 5V$, $R_L = 2k\Omega$ to GND, G = +2, $R_F = 1.5k\Omega$; unless otherwise noted.

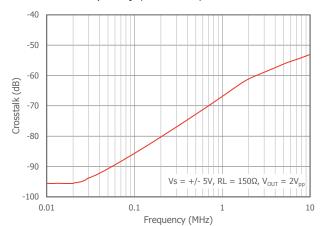
Non-Inverting Large Signal Pulse Response



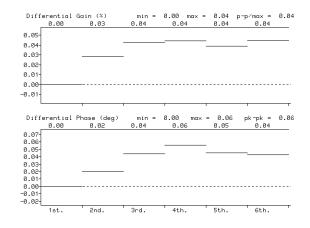
Differential Gain & Phase_DC Coupled



Crosstalk vs Frequency (CLC2007)



Differential Gain & Phase_AC Coupled



Application Information

General Description

The CLC1007, CLC2007, and CLC4007 are single supply, general purpose, voltage-feedback amplifiers fabricated on a complementary bipolar process using a patent pending topography. They feature a rail-to-rail output stage and is unity gain stable. Both gain bandwidth and slew rate are insensitive to temperature.

The common mode input range extends to 300mV below ground and to 0.9V below V_s. Exceeding these values will not cause phase reversal. However, if the input voltage exceeds the rails by more than 0.5V, the input ESD devices will begin to conduct. The output will stay at the rail during this overdrive condition.

The design is short circuit protected and offers "soft" saturation protection that improves recovery time.

Figures 1, 2, and 3 illustrate typical circuit configurations for non-inverting, inverting, and unity gain topologies for dual supply applications. They show the recommended bypass capacitor values and overall closed loop gain equations. Figure 4 shows the typical non-inverting gain circuit for single supply applications.

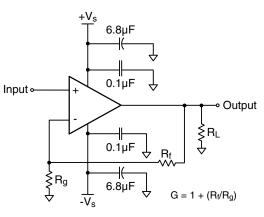
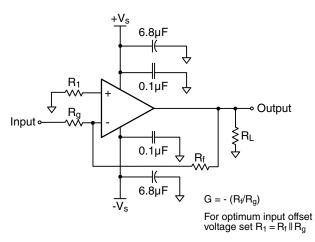


Figure 1: Typical Non-Inverting Gain Circuit





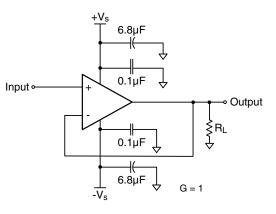


Figure 3: Unity Gain Circuit

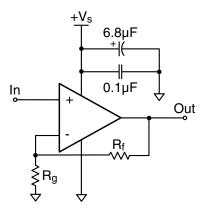


Figure 4: Single Supply Non-Inverting Gain Circuit

Overdrive Recovery

For an amplifier, an overdrive condition occurs when the output and/or input ranges are exceeded. The recovery time varies based on whether the input or output is overdriven and by how much the ranges are exceeded. The CLC1007, CLC2007, and CLC4007 will typically recover in less than 20ns from an overdrive condition. Figure 5 shows the CLC2007 in an overdriven condition.

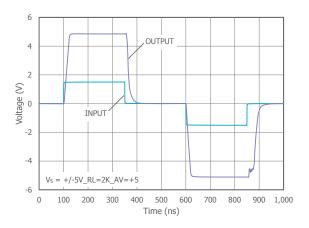


Figure 5: Overdrive Recovery

Power Dissipation

Power dissipation should not be a factor when operating under the stated $2k\Omega$ load condition. However, applications with low impedance, DC coupled loads should be analyzed to ensure that maximum allowed junction temperature is not exceeded. Guidelines listed below can be used to verify that the particular application will not cause the device to operate beyond it's intended operating range.

Maximum power levels are set by the absolute maximum junction rating of 170°C. To calculate the junction temperature, the package thermal resistance value Theta_{JA} (θ_{JA}) is used along with the total die power dissipation.

$$T_{\text{Junction}} = T_{\text{Ambient}} + (\theta_{\text{JA}} \times P_{\text{D}})$$

Where $\mathsf{T}_{\mathsf{Ambient}}$ is the temperature of the working environment.

In order to determine P_D , the power dissipated in the load needs to be subtracted from the total power delivered by the supplies.

$$P_D = P_{supply} - P_{load}$$

Supply power is calculated by the standard power equation.

$$P_{supply} = V_{supply} \times I_{RMSsupply}$$
$$V_{supply} = V_{S+} - V_{S-}$$

Power delivered to a purely resistive load is:

$$P_{load} = ((V_{load})_{RMS^2})/Rload_{eff}$$

The effective load resistor ($Rload_{eff}$) will need to include the effect of the feedback network. For instance,

Rload_{eff} in Figure 3 would be calculated as:

$$R_L \parallel (R_f + R_g)$$

These measurements are basic and are relatively easy to perform with standard lab equipment. For design purposes however, prior knowledge of actual signal levels and load impedance is needed to determine the dissipated power. Here, P_D can be found from

$$P_D = P_{Quiescent} + P_{Dynamic} - P_{load}$$

Quiescent power can be derived from the specified $I_{\rm S}$ values along with known supply voltage, V_{supply} . Load power can be calculated as above with the desired signal amplitudes using:

$$(V_{load})_{RMS} = V_{peak} / \sqrt{2}$$

$$(I_{load})_{RMS} = (V_{load})_{RMS} / Rload_{eff}$$

The dynamic power is focused primarily within the output stage driving the load. This value can be calculated as:

 $P_{Dynamic} = (V_{S+} - V_{load})_{RMS} \times (I_{load})_{RMS}$

Assuming the load is referenced in the middle of the power rails or $V_{supply}/2$.

The CLC1007 is short circuit protected. However, this may not guarantee that the maximum junction temperature (+150°C) is not exceeded under all conditions. Figure 6 shows the maximum safe power dissipation in the package vs. the ambient temperature for the packages available.

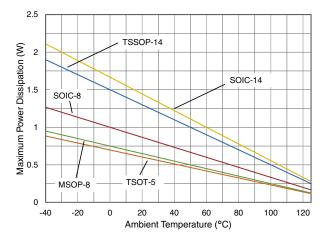


Figure 6. Maximum Power Derating

Driving Capacitive Loads

Increased phase delay at the output due to capacitive loading can cause ringing, peaking in the frequency response, and possible unstable behavior. Use a series resistance, R_S , between the amplifier and the load to help improve stability and settling performance. Refer to Figure 7.

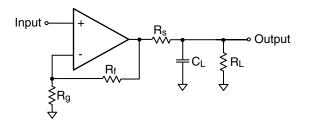


Figure 7. Addition of R_S for Driving Capacitive Loads

Table 1 provides the recommended R_S for various capacitive loads. The recommended R_S values result in approximately <1dB peaking in the frequency response.

C _L (pF)	R _S (Ω)	-3dB BW (MHz)
22pF	0	118
47pF	15	112
100pF	15	91
492pF	6.5	59

Table 1: Recommended R_S vs. C_L

For a given load capacitance, adjust R_S to optimize the tradeoff between settling time and bandwidth. In general, reducing R_S will increase bandwidth at the expense of additional overshoot and ringing.

Layout Considerations

General layout and supply bypassing play major roles in high frequency performance. Exar has evaluation boards to use as a guide for high frequency layout and as an aid in device testing and characterization. Follow the steps below as a basis for high frequency layout:

- Include 6.8µF and 0.1µF ceramic capacitors for power supply decoupling
- Place the 6.8µF capacitor within 0.75 inches of the power pin
- Place the 0.1µF capacitor within 0.1 inches of the power pin
- Remove the ground plane under and around the part, especially near the input and output pins to reduce parasitic capacitance
- Minimize all trace lengths to reduce series inductances

Refer to the evaluation board layouts below for more information.

Evaluation Board Information

The following evaluation boards are available to aid in the testing and layout of these devices:

Evaluation Board #	Products
CEB002	CLC1007 in TSOT
CEB003	CLC1007 in SOIC
CEB006	CLC2007 in SOIC
CEB010	CLC2007 in MSOP
CEB018	CLC4007 in SOIC
CEB019	CLC4007 in TSSOP

Evaluation Board Schematics

Evaluation board schematics and layouts are shown in Figures 8-20. These evaluation boards are built for dualsupply operation. Follow these steps to use the board in a single-supply application:

- 1. Short -V $_{\rm S}$ to ground.
- 2. Use C3 and C4, if the -V_S pin of the amplifier is not directly connected to the ground plane.

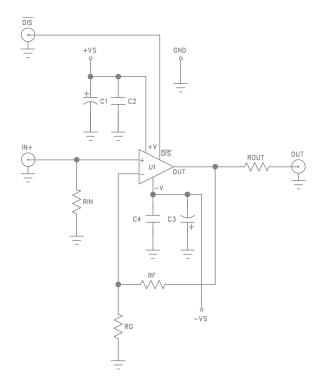


Figure 8. CEB002 & CEB003 Schematic

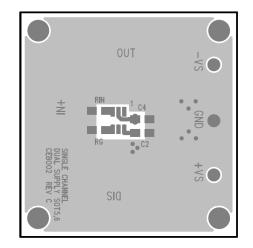


Figure 9. CEB002 Top View

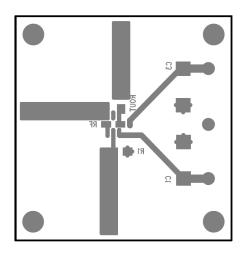


Figure 10. CEB002 Bottom View

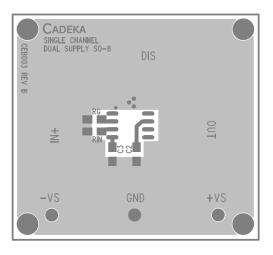


Figure 11. CEB003 Top View

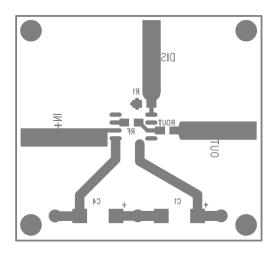


Figure 12. CEB003 Bottom View

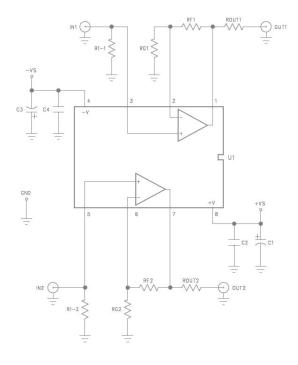


Figure 13. CEB006 & CEB010 Schematic

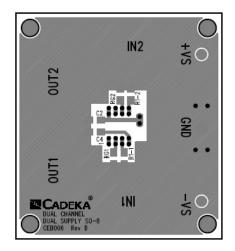


Figure 14. CEB006 Top View

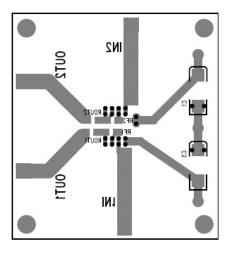


Figure 15. CEB006 Bottom View

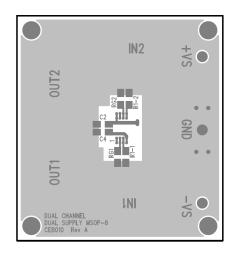


Figure 16. CEB010 Top View

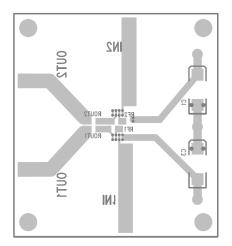


Figure 17. CEB010 Bottom View

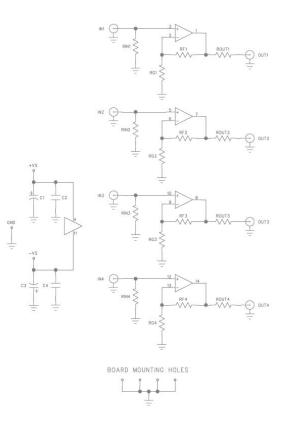


Figure 18. CEB018 Schematic

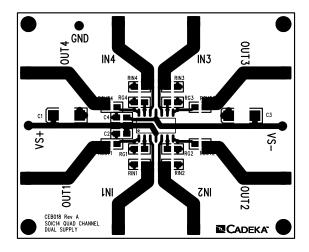


Figure 19. CEB018 Top View

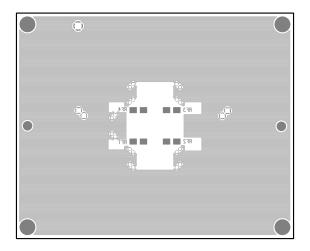
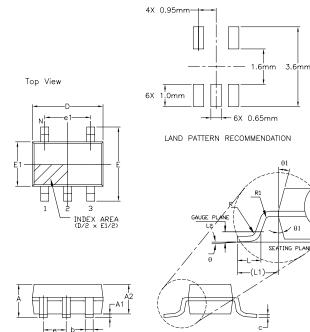


Figure 20. CEB018 Bottom View

Mechanical Dimensions

TSOT-5 Package



3.6mm

A.

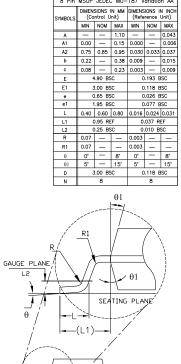
/>								
5 Pin TSOT (OPTION 2)								
SYMBOLS		ISION II ntrol U		DIMENSION IN INCH (Reference Unit)				
	MIN	NOM	MAX	MIN	NOM	MAX		
A	0.75	_	0.80	0.030	—	0.031		
A1	0.00	_	0.05	0.000	-	0.002		
A2	0.70	0.75	0.78	0.028	0.030	0.031		
b	0.35	—	0.50	0.012	—	0.020		
с	0.10	_	0.20	0.003	_	0.008		
D	2	.90 BS	SC	0.114 BSC				
E	2	.80 BS	SC .	0.110 BSC				
E1	1	.60 BS	SC	0.063 BSC				
е	C	.95 BS	SC .	0.038 BSC				
e1	1	.90 BS	SC	0.075 BSC				
L	0.37	0.45	0.60	0.012	0.018	0.024		
L1	0).60 RE	F	0.024 REF				
L2	0.25 BSC			0.010 BSC				
R	0.10	_	_	0.004	_	_		
R1	0.10	_	0.25	0.004	—	0.010		
θ	0.	4'	8'	0.	4'	8'		
θ1	4.	10*	12*	4*	10*	12		
N		5		5				

Side View

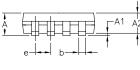
Front View

MSOP-8 Package

Top View Ν П 2 З 1 INDEX AREA



8 Pin MSOP JEDEC MO-187 Variation AA

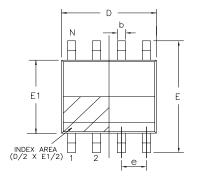


Side View

Front View

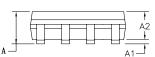
EXAR

SOIC-8 Package



Top View

Side View





1.98mm

Front View

45

RECOMMENDED PCB LAND PATTERN

0.53mm

- | |-

1.27mm

\01

4.93mm

<u>θ2</u>

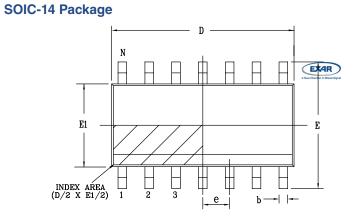
GAUGE PLANE

SEATING PLANE

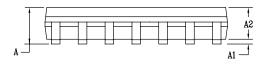
-L2

Ν

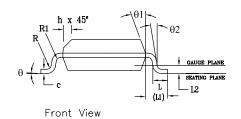
8 Pin SOICN JEDEC MS-012 Variation AA								
SYMBOLS		NSIONS II ontrol Un		DIMENSIONS IN INCH (Reference Unit)				
	MIN	NOM	MAX	MIN	NOM	MAX		
A	1.35	—	1.75	0.053		0.069		
A1	0.10	—	0.25	0.004	_	0.010		
A2	1.25	—	1.65	0.049	—	0.065		
b	0.31	—	0.51	0.012	_	0.020		
С	0.17	—	0.25	0.007		0.010		
E	6	5.00 BSC)	0.236 BSC				
E1		3.90 BSC)	0.154 BSC				
е		1.27 BSC)	0.050 BSC				
h	0.25	—	0.50	0.010		0.020		
L	0.40	_	1.27	0.016	_	0.050		
L1		1.04 REF		0.041 REF				
L2		0.25 BSC	2	0.010 BSC				
R	0.07	—	_	0.003	_	—		
R1	0.07		_	0.003	_	—		
θ	0. —		8*	0°	_	8'		
θ1	5°	_	15°	5°	_	15°		
θ2	0. —		_	0°	_	_		
D	4	4.90 BSC	:	0.193 BSC				
N		8			8			



Top View

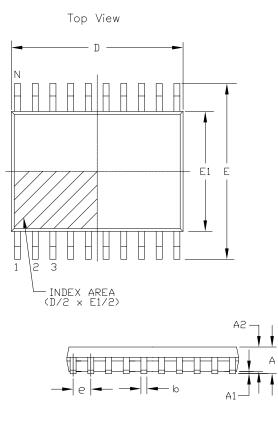


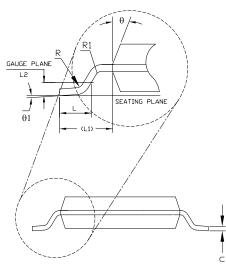
Side View



PACKAGE OUTLINE NSOIC .150" BODY JEDEC MS-012												
SYMBO	LS	COMMON DIMENSIONS IN MM (Control Unit)			мм	COMMON DIMENSIONS IN INCH (Reference Unit)						
		M	IN	NOM	MA	х	MIN	NOM	MAX			
Α		1.	35	—	1.7	75	0.053	_	0.069			
A1		0.	10	—	0.2	25	0.004	—	0.010			
A2		1.	25	—	1.6	65	0.049	_	0.065			
р		0.	.31	-	0.5	51	0.012	_	0.020			
с		0.	17	-	0.2	25	0.007	_	0.010			
E				6.00 BS(2		0	.236 BS	iC			
E1				3.90 BS	С		0	.154 BS	BSC BSC			
e				1.27 BS	С		0	.050 BS	0 BSC			
h		0.	25	—	0.5	50	0.010	_	0.020			
L		0.4	40	—	1.2	7	0.016	_	0.050			
L1		1.04 REF					0.041 REF					
L2				0.25 BS	<u>c</u>		0.010 BSC					
R		0.	07	—	-	-	0.003	_	—			
R1			07	—	-	-	0.003	—	—			
θ		(с.	-	8	•	0.	—	8'			
θ1			5*	—	15	5'	5'	_	15'			
θ2		1	o.	—	-	-	0'	_	—			
D					SEE \	/ARI,	ATIONS					
Ν					SEE \	/ARI	ATIONS					
VARIATION D												
VARIATIONS	1	DIMENSIONS IN MM (Control Unit)			M C	DIMENSIONS IN INCH (Reference Unit)			N			
SNO	MI	N	NO	M MA	хI	MIN	NOM	MAX				
AA		4.90 BSC					0.193 E	ISC	8			
AB		8	.65	BSC			0.341 E	ISC	14			
AC		9.90 BSC 0.390 BSC 16						16				

TSSOP-14 Package





Front View

Side View

14 Pin TSSOP JEDEC M0-153 Variation AB-1								
SYMBOLS		NSIONS ontrol U		DIMENSIONS IN INCH (Reference Unit)				
	MIN	NOM	MAX	MIN	NOM	MAX		
A	—	_	1.20	—	—	0.047		
A1	0.05	_	0.15	0.002	—	0.006		
A2	0.80	1.00	1.05	0.031	0.039	0.041		
b	0.19	0.30	0.007	—	0.012			
с	0.09	_	0.20	0.004	—	0.008		
E	6	.40 BS	iC	0.252 BSC				
E1	4.30	4.40	4.50	0.169	0.173	0.177		
е	C	.65 BS	SC SC	0.026 BSC				
L	0.45 0.60		0.75	0.018	0.024	0.030		
L1	1	.00 RE	F	0.039 REF				
L2	0).25 BS	SC	0.010 BSC				
R	0.09	-	—	0.035	—	—		
R1	0.09	—	—	0.035	—	_		
θ	1	2° RE	F	12" REF				
θ1	0°	_	8*	0*	_	8'		
D	4.90	5.00	5.10	0.193	0.197	0.200		
N		14		14				